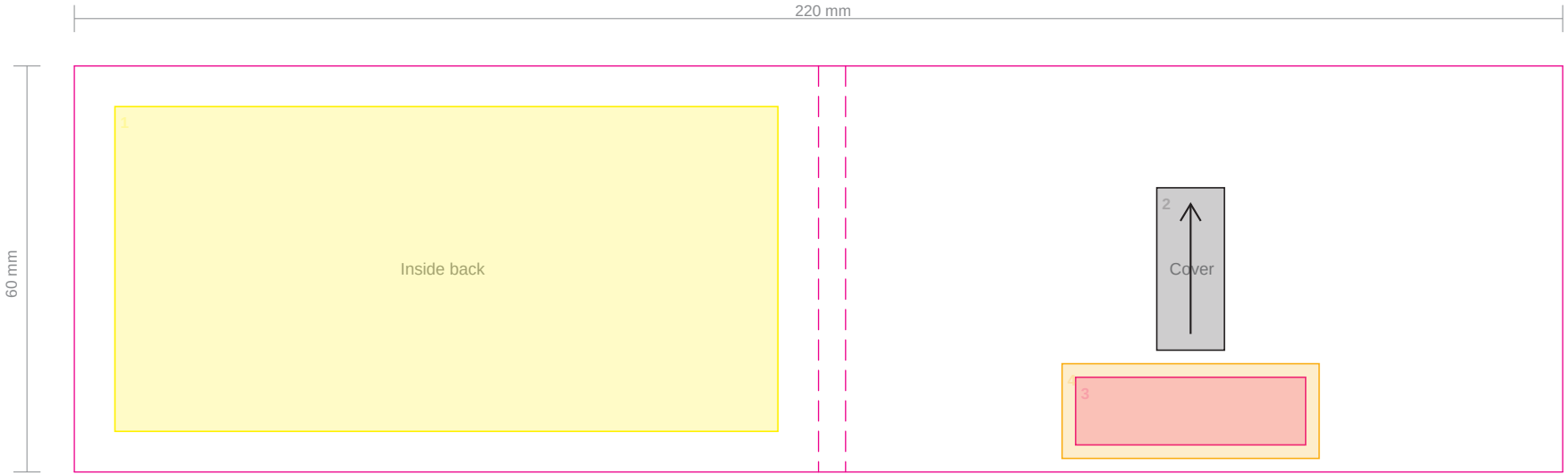


packart.dev · Dieline catalogue

Blister wallet, bi-fold

PA-WA-001 · Wallet
Die extent: 220 × 60 mm (TrimBox)
Market: EU

Separations: Dieline (cut solid, crease 3/1.5 mm, perf 0.8/0.8 mm), Kiss cut, Technical, TP … — all non-printing, overprint.

Technical profile: Wallet · compliance pack

Board wallet with blister, online coding

1 Blister seal / glue area [Glue area]
98 × 48 mm at 6 / 6 · Method: Hot melt dots
No ink and no varnish where the blister is sealed or glued.

2 Reading direction [Reading direction]
10 × 24 mm at 160 / 18 · Direction: up

3 LOT / EXP [Variable data / coding]
34 × 10 mm at 148 / 46 · Method: Inkjet

4 Coding window [Varnish-free area]
38 × 14 mm at 146 / 44

Sample: parametric reconstruction of a standard style. Not a supplier die — not for production.
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